<u>Onsemí</u>,

MOSFET – N-Channel, UniFET™, FRFET[®]

400 V, 23 A, 190 m Ω

FDA24N40F

Description

UniFET MOSFET is **onsemi**'s high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. The body diode's reverse recovery performance of UniFET FRFET MOSFET has been enhanced by lifetime control. Its trr is less than 100 ns and the reverse dv/dt immunity is 15 V/ns while normal planar MOSFETs have over 200 ns and 4.5 V/ns respectively. Therefore, it can remove additional component and improve system reliability in certain applications in which the performance of MOSFET's body diode is significant. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.

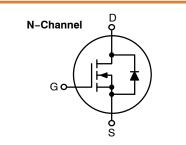
Features

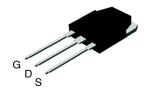
- $R_{DS(on)} = 150 \text{ m}\Omega \text{ (Typ.)} @ V_{GS} = 10 \text{ V}, I_D = 11.5 \text{ A}$
- Low Gate Charge (Typ. 46 nC)
- Low C_{rss} (Typ. 25 pF)
- 100% Avalanche Tested
- RoHS Compliant

Applications

- Uninterruptible Power Supply
- AC-DC Power Supply

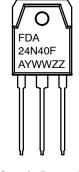
V _{DS}	R _{DS(ON)} MAX	I _D MAX	
400 V	190 mΩ @ 10 V	23 A	





TO-3P-3LD / EIAJ SC-65, ISOLATED CASE 340BZ

MARKING DIAGRAM



FDA24N40F	= Specific Device Code
A	= Assembly Site
YWW	= Date Code (Year & Work Week)
ZZ	= Assembly Lot Number

ORDERING INFORMATION

Device	i usinge s	
FDA24N40F	TO-3P-3LD	450 Units / Tube

MOSFET MAXIMUM RATINGS (T_C = 25° C unless otherwise noted)

Symbol	Paramete	r	Value	Unit	
V _{DSS}	Drain to Source Voltage	400	V		
V _{GSS}	Gate to Source Voltage	Gate to Source Voltage			
I _D	Drain Current	– Continuous (T _C = 25°C)	23	Α	
		– Continuous (T _C = 100°C)	13.8		
I _{DM}		- Pulsed (Note 1)	92		
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	le Pulsed Avalanche Energy (Note 2)			
I _{AR}	Avalanche Current (Note 1)	23	Α		
E _{AR}	Repetitive Avalanche Energy (Note 1)		23.5	mJ	
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5	V/ns	
PD	Power Dissipation	$T_{C} = 25^{\circ}C$	235	W	
		-Derate above = 25°C	1.8	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range	•	–55 to +150	°C	
TL	Maximum Lead Temperature for Soldering, 1/8" fr	om Case for 5 Seconds	300	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Repetitive rating: pulse-width limited by maximum junction temperature. 2. L = 4.5 mH, I_{AS} = 23 A, V_{DD} = 50 V, R_G = 25 Ω , starting T_J = 25°C. 3. $I_{SD} \le$ 23 A, di/dt \le 200 A/µs, $V_{DD} \le$ BV_{DSS}, starting T_J = 25°C.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.53	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

ELECTRICAL CHARACTERISTICS (T_J = 25° C unless otherwise noted)

Parameter	Test Conditions	Min	Тур	Max	Unit
CTERISTICS	-	-	-		
Drain to Source Breakdown Voltage	I_D = 250 $\mu A,V_{GS}$ = 0 V, T_J = 25°C	400	_	-	V
Breakdown Voltage Temperature Coefficient	$I_D = 250 \ \mu$ A, referenced to 25° C	-	0.5	-	V/°C
Zero Gate Voltage Drain Current	$V_{DS} = 400 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	10	μA
	V_{DS} = 320 V, T_{C} = 125°C	-	-	100	
Gate to Body Leakage Current	V_{GS} = ±30 V, V_{DS} = 0 V	-	_	±100	nA
	CTERISTICS Drain to Source Breakdown Voltage Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current	CTERISTICSDrain to Source Breakdown Voltage $I_D = 250 \ \mu\text{A}, \ V_{GS} = 0 \ V, \ T_J = 25^{\circ}\text{C}$ Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu\text{A}, \ referenced to 25^{\circ}\text{C}$ Zero Gate Voltage Drain Current $V_{DS} = 400 \ V, \ V_{GS} = 0 \ V$ $V_{DS} = 320 \ V, \ T_C = 125^{\circ}\text{C}$	CTERISTICSDrain to Source Breakdown Voltage $I_D = 250 \ \mu\text{A}, \ V_{GS} = 0 \ V, \ T_J = 25^{\circ}\text{C}$ 400Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu\text{A}, \ referenced to 25^{\circ}\text{C}$ -Zero Gate Voltage Drain Current $V_{DS} = 400 \ V, \ V_{GS} = 0 \ V$ - $V_{DS} = 320 \ V, \ T_C = 125^{\circ}\text{C}$ -	CTERISTICSDrain to Source Breakdown Voltage $I_D = 250 \ \mu A, V_{GS} = 0 \ V, T_J = 25^{\circ}C$ 400-Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu A, referenced to 25^{\circ}C$ -0.5Zero Gate Voltage Drain Current $V_{DS} = 400 \ V, V_{GS} = 0 \ V$ $V_{DS} = 320 \ V, T_C = 125^{\circ}C$	CTERISTICSDrain to Source Breakdown Voltage $I_D = 250 \ \mu$ A, $V_{GS} = 0 \ V$, $T_J = 25^{\circ}$ C 400 $ -$ Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu$ A, referenced to 25° C $ 0.5$ $-$ Zero Gate Voltage Drain Current $V_{DS} = 400 \ V$, $V_{GS} = 0 \ V$ $ 10$ $V_{DS} = 320 \ V$, $T_C = 125^{\circ}$ C $ 100$

V _{GS(th)}	Gate Threshold Voltage	V_{GS} = V_{DS} , I_D = 250 μ A	3.0	-	5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 11.5 A	-	0.15	0.19	Ω
9FS	Forward Transconductance	V _{DS} = 20 V, I _D = 11.5 A	-	29	-	S

DYNAMIC CHARACTERISTICS

C _{iss}	Input Capacitance	V_{DS} = 25 V, V_{GS} = 0 V, f = 1 MHz	-	2280	3030	pF
C _{oss}	Output Capacitance		-	370	490	pF
C _{rss}	Reverse Transfer Capacitance		-	25	38	pF
Q _{g(tot)}	Total Gate Charge at 10 V	$V_{DS} = 320 \text{ V}, \text{ I}_{D} = 23 \text{ A}, \text{ V}_{GS} = 10 \text{ V}$	-	46	60	nC
Q _{gs}	Gate to Source Gate Charge	(Note 4)	-	13	-	nC
Q _{gd}	Gate to Drain "Miller" Charge		-	18	-	nC

SWITCHING CHARACTERISTICS

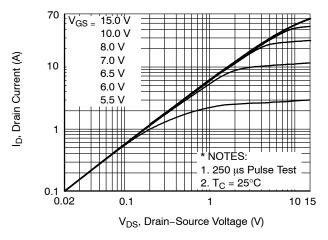
t _{d(on)}	Turn-On Delay Time	$V_{DS} = 200 \text{ V}, I_D = 23 \text{ A}, V_{GS} = 10 \text{ V},$	-	40	90	ns
t _r	Turn–On Rise Time	R _G = 25 Ω (Note 4)	-	92	195	ns
t _{d(off)}	Turn-Off Delay Time		-	120	250	ns
t _f	Turn-Off Fall Time		-	75	160	ns

DRAIN-SOURCE DIODE CHARACTERISTICS

I _S	Maximum Continuous Drain to Source Di	Maximum Continuous Drain to Source Diode Forward Current		-	23	А
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	92	А
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, \text{ I}_{SD} = 23 \text{ A}$	-	-	1.5	V
t _{rr}	Reverse Recovery Time	V_{GS} = 0 V, I_{SD} = 23 A, dI_F/dt = 100 A/ μs	-	110	-	ns
Q _{rr}	Reverse Recovery Charge		-	0.3	_	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Essentially independent of operating temperature typical characteristics.

TYPICAL PERFORMANCE CHARACTERISTICS





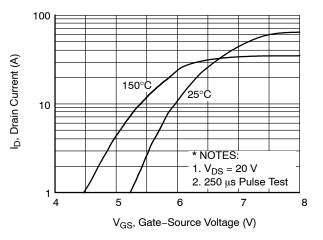


Figure 2. Transfer Characteristics

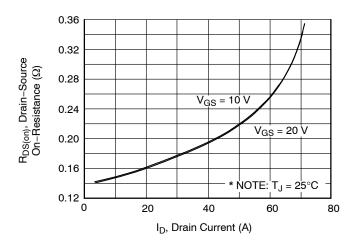


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

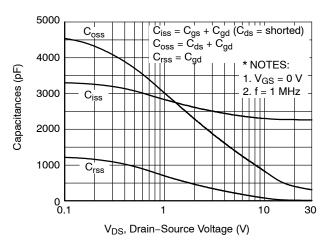


Figure 5. Capacitance Characteristics

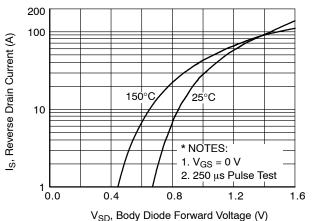


Figure 4. Body Diode Forward Voltage Variation vs. Source Current And Temperature

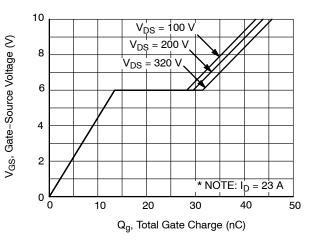


Figure 6. Gate Charge Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

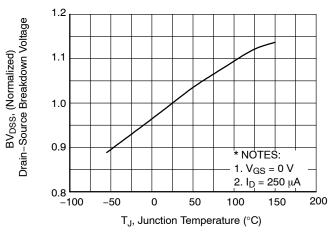


Figure 7. Breakdown Voltage Variation vs. Temperature

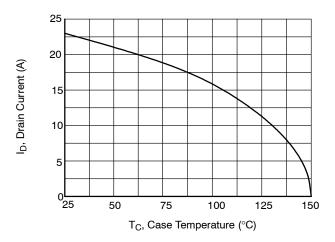


Figure 9. Maximum Drain Current vs. Case Temperature

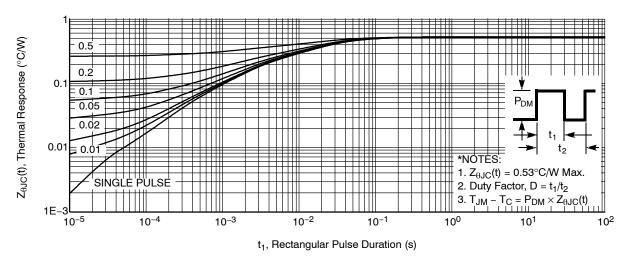


Figure 10. Transient Thermal Response Curve

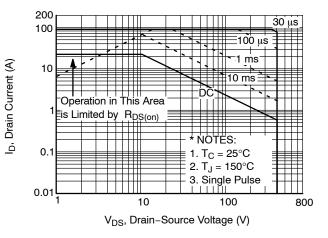
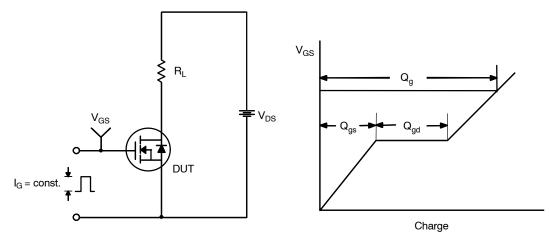


Figure 8. Maximum Safe Operating Area





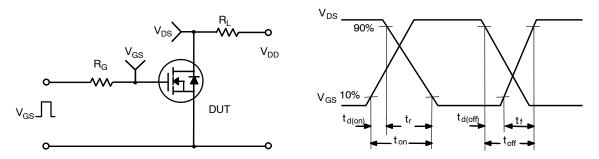


Figure 12. Resistive Switching Test Circuit & Waveforms

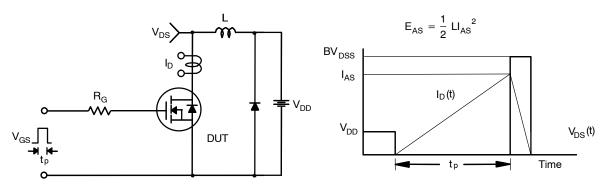


Figure 13. Unclamped Inductive Switching Test Circuit & Waveforms

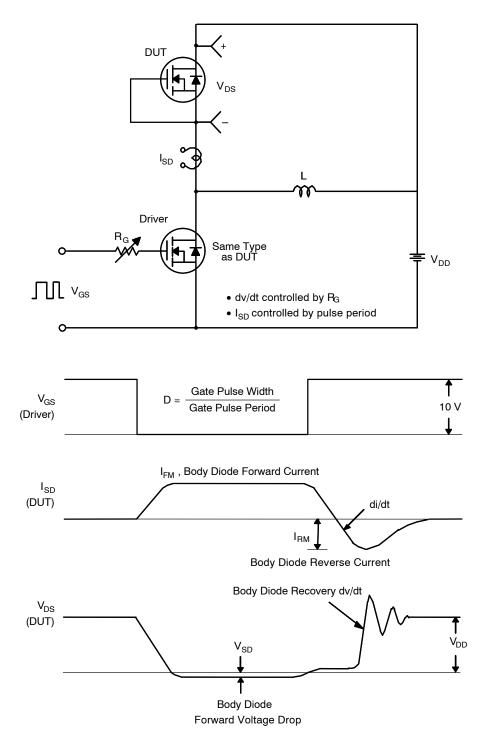


Figure 14. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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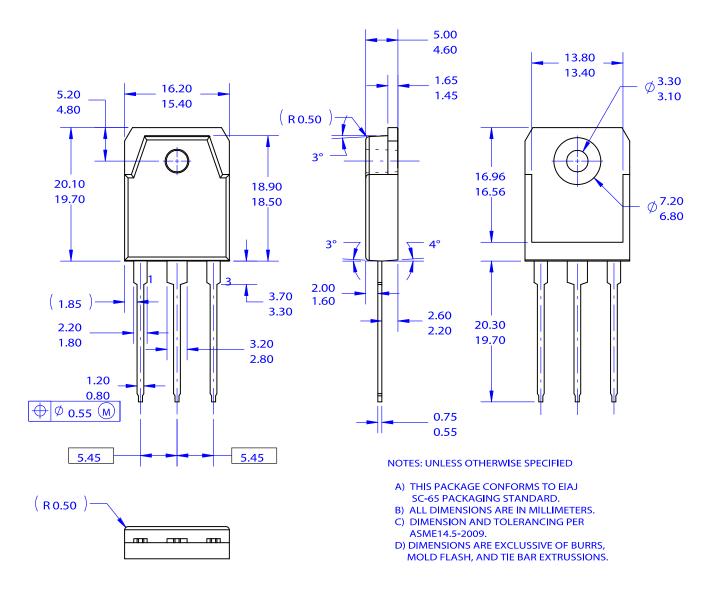
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